# 2SD2067

## Silicon NPN epitaxial planar type

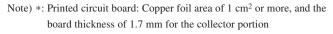
### For low-frequency output amplification

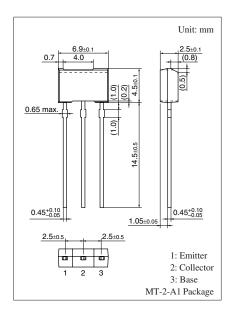
#### ■ Features

- Darlington connection
- $\bullet$  High forward current transfer ratio  $h_{FE}$
- $\bullet$  Large peak collector current  $I_{\mbox{\footnotesize{CP}}}$
- ullet High collector-emitter voltage (Base open)  $V_{CEO}$
- Allowing supply with the radial taping

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	120	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	100	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_C$	2	A
Peak collector current	$I_{CP}$	3	A
Collector power dissipation *	P <sub>C</sub>	1	W
Junction temperature	$T_j$	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C





### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 100 \ \mu A, I_E = 0$	120			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 1 \text{ mA}, I_B = 0$	100			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 100 \ \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 25 \text{ V}, I_{E} = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 4 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio *1, 2	h <sub>FE</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ A}$	4000		40 000	_
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 1 \text{ A}, I_B = 1 \text{ mA}$			1.5	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 1 \text{ A}, I_B = 1 \text{ mA}$			2	V

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

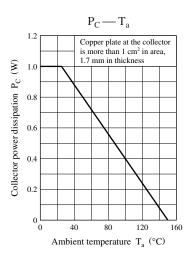
#### 2. \*1: Pulse measurement

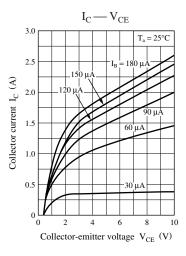
#### \*2: Rank classification

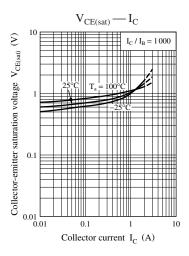
Rank	Q	R	S
$h_{\mathrm{FE}}$	4000 to 10000	8 000 to 20 000	16 000 to 40 000

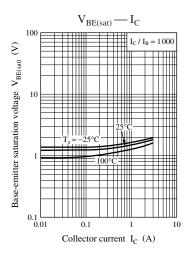
Publication date: April 2003 SJC00240BED 1

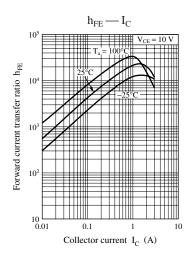
## **Panasonic**

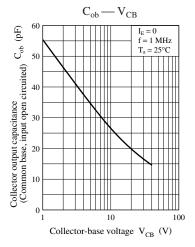


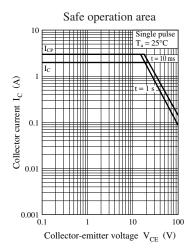












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